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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:		NEW ASSIGNMENT				
NATURE OF CONVEYANCE:			ASSIGNMENT			
CONVEYING PARTY	DATA					
			Name		E	xecution Date
SOMAN NIKHARA					10	/23/2017
RAVI SHANKAR KADAMBALA					10	/23/2017
BAPINEEDU CHOWD	ARY GUN	1MADI			10	/23/2017
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State/Country:	CALIF	CALIFORNIA				
Postal Code:	92121-	92121-1714				
Application Number:		1571	5710752			
Property Type Application Number:		1571	Number 15710752			
	DATA					
CORRESPONDENCE Fax Number:	DATA					
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SIGNATURE:		/Tanya Yee/				
DATE SIGNED:		11/13/2017				
Total Attachments: 3						
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PATENT QUALCOMM Ref. No. 170432 Page 1 of 3

ASSIGNMENT

WHEREAS, WE,

1. Soman NIKHARA, a citizen of the India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of Hyderabad, IN,

2. Ravi Shankar KADAMBALA, a citizen of the India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of Hyderabad, IN,

3. Bapineedu Chowdary GUMMADI, a citizen of the India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of Hyderabad, IN,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to SYSTEM AND METHOD FOR IMPROVED CAMERA FLASH (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS, including but not limited to, U.S. Application No(s). 15/710,752 filed September 20, 2017, Qualcomm Reference No. 170432, and all provisional applications relating thereto, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all nonprovisional applications, national phase applications, divisional applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have

PATENT REEL: 044113 FRAME: 0436 granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

> PATENT REEL: 044113 FRAME: 0437

PATENT QUALCOMM Ref. No. 170432 Page 3 of 3

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _	Wyeleseland	, on 23 who ct 2017	burnt .			
	LOCATION	DATE	Soman NIKHARA			
Done at _	My Jenson J	, on 23 Hud 2017	K-hathankan			
	LOCATION	DATE	Ravi Shankar KADAMBALA			
Done at _	Hydenabad	.m 23" oct 2017	G. Bogersad			
	LOCATION	DATE	Bapineedu Chowdary GUMMADI			

RECORDED: 11/13/2017